

## Description

The SXG130N10NF uses advanced technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## General Features

$V_{DS} = 100V$   $I_D = 130A$

$R_{DS(ON)} < 4.2m\Omega$  @  $V_{GS}=10V$

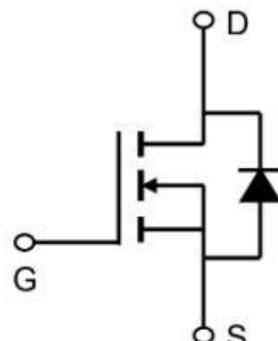
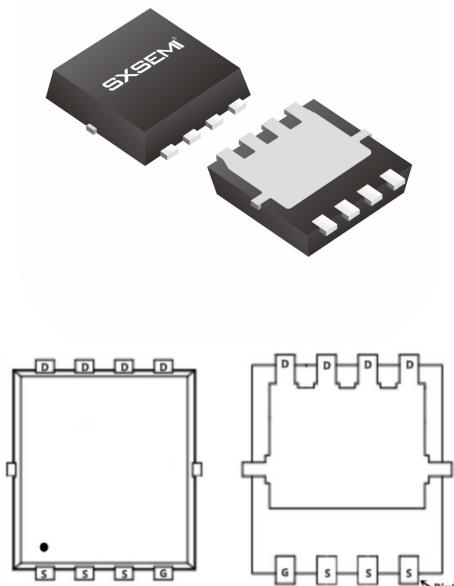
## Application

Isolated DC

Motor control

Synchronous-rectification

PDFN5\*6-8L



## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

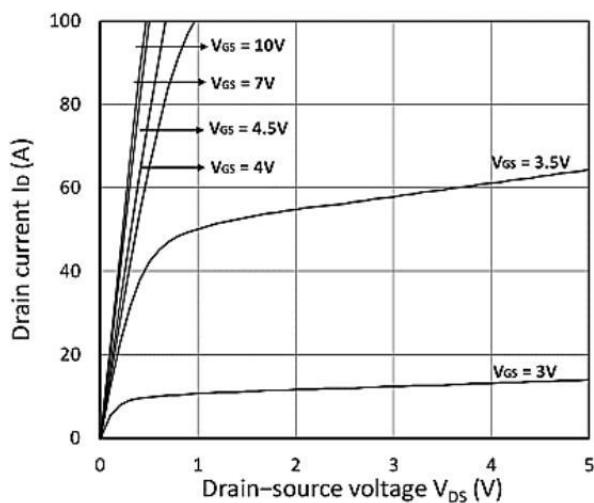
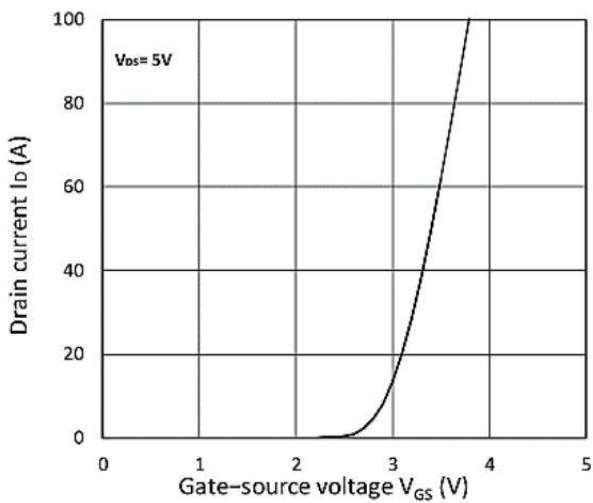
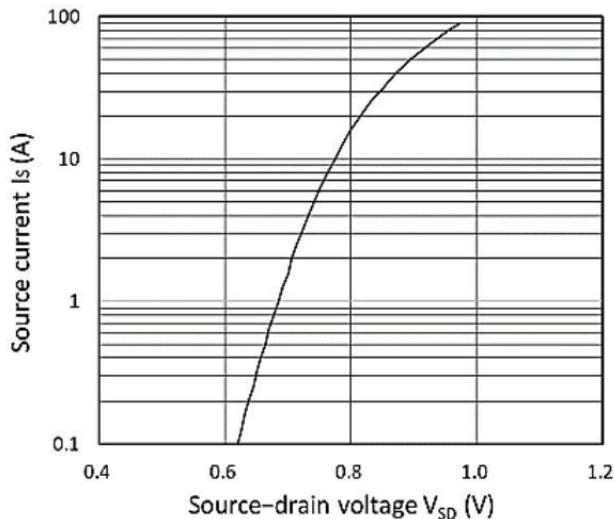
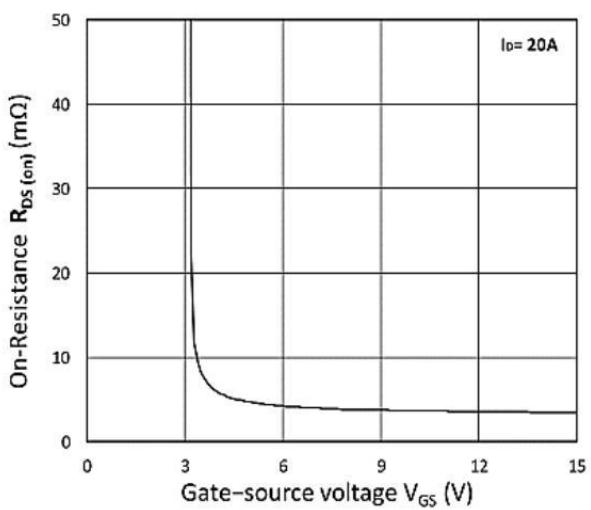
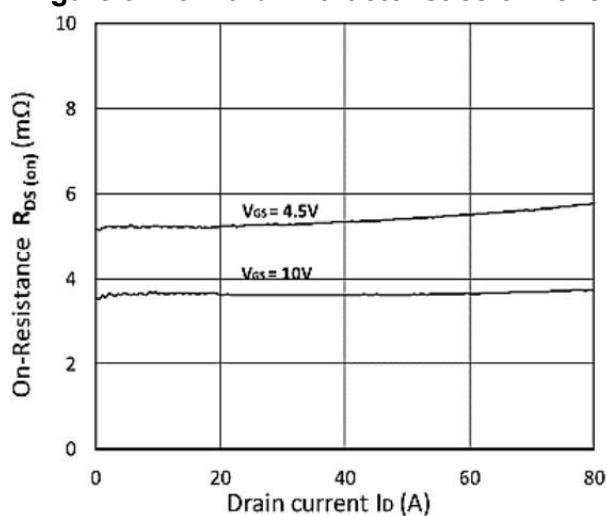
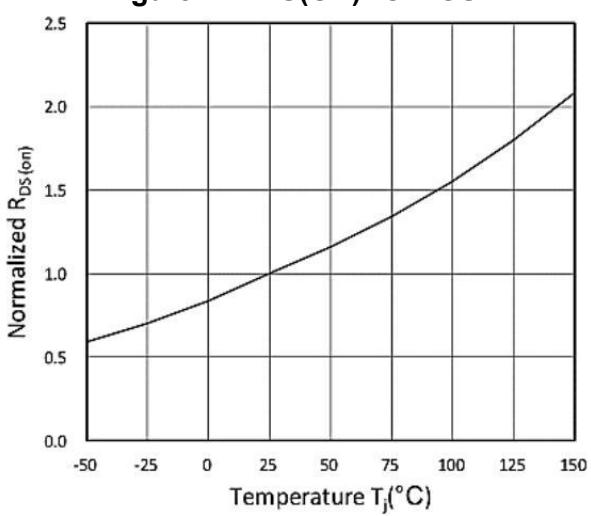
Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current <sup>1</sup>	130	A
$I_D@T_A=70^\circ C$	Continuous Drain Current <sup>1</sup>	78	A
$IDM$	Pulsed Drain Current <sup>2</sup>	480	A
$EAS$	Single Pulse Avalanche Energy <sup>3</sup>	320	mJ
$IAS$	Avalanche Current	40	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	131.6	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	25	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	0.95	°C/W

**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

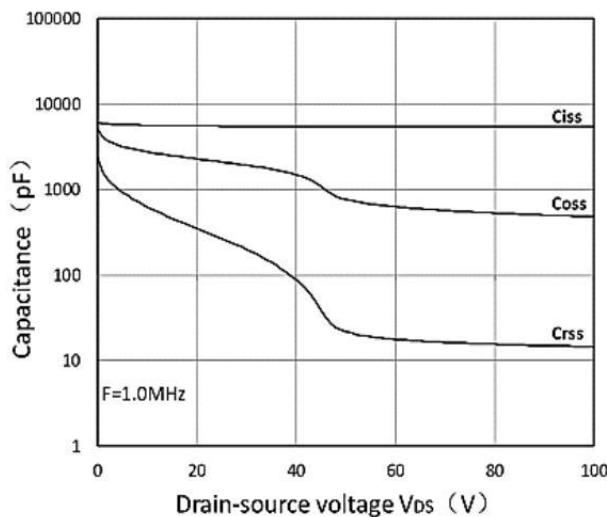
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$ , $I_D = 250\mu\text{A}$	100	107	-	V
IGSS	Gate-body Leakage current	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
IDSS	Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$V_{DS} = 100\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
	Zero Gate Voltage Drain Current $T_J=100^\circ\text{C}$		-	-	100	
VGS(th)	Gate-Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	1.2	1.8	2.5	V
RDS(on)	Drain-Source on-Resistance <sup>4</sup>	$V_{GS} = 10\text{V}$ , $I_D = 20\text{A}$	-	3.2	4.5	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}$ , $I_D = 15\text{A}$	-	5.2	6.7	
gfs	Forward Transconductance <sup>4</sup>	$V_{DS} = 10\text{V}$ , $I_D = 20\text{A}$	-	70	-	S
Ciss	Input Capacitance	$V_{DS} = 50\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$	-	5475	-	$\text{pF}$
Coss	Output Capacitance		-	768	-	
Crss	Reverse Transfer Capacitance		-	22	-	
R <sub>g</sub>	Gate Resistance	$f = 1\text{MHz}$	-	1.3	-	$\Omega$
Q <sub>g</sub>	Total Gate Charge	$V_{GS} = 10\text{V}$ , $V_{DS} = 50\text{V}$ , $I_D = 20\text{A}$	-	111.2	-	$\text{nC}$
Q <sub>gs</sub>	Gate-Source Charge		-	17.5	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	30.2	-	
td(on)	Turn-on Delay Time	$V_{GS} = 10\text{V}$ , $V_{DD} = 50\text{V}$ , $R_G = 3\Omega$ , $I_D = 20\text{A}$	-	22.2	-	$\text{ns}$
t <sub>r</sub>	Rise Time		-	37.8	-	
td(off)	Turn-off Delay Time		-	95.2	-	
t <sub>f</sub>	Fall Time		-	35.6	-	
t <sub>rr</sub>	Body Diode Reverse Recovery Time	$I_F = 20\text{A}$ , $dI/dt = 100\text{A}/\mu\text{s}$	-	59.4	-	$\text{ns}$
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	91.8	-	
VSD	Diode Forward Voltage <sup>4</sup>	$I_S = 20\text{A}$ , $V_{GS} = 0\text{V}$	-	-	1.2	V
I <sub>S</sub>	Continuous Source Current $T_c=25^\circ\text{C}$	-	-	-	120	A

**Note :**

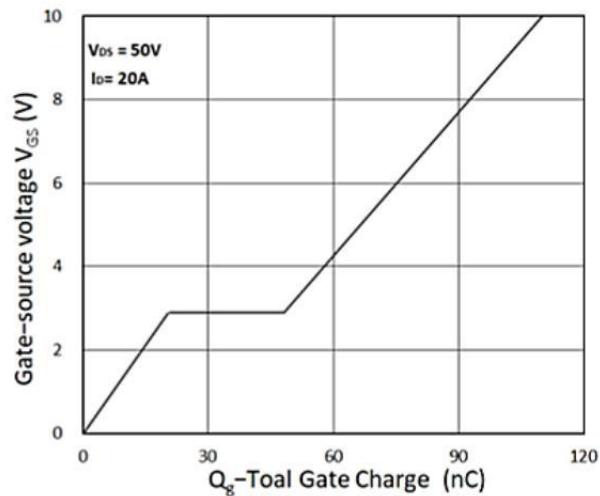
- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $V_{DD}=72\text{V}$ , $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$   $I_{AS}=40\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation

**Typical Characteristics****Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Forward Characteristics of Reverse****Figure 4. RDS(ON) vs. VGS****Figure 5. RDS(ON) vs. ID****Figure 6. Normalized RDS(on) vs. Temperature**

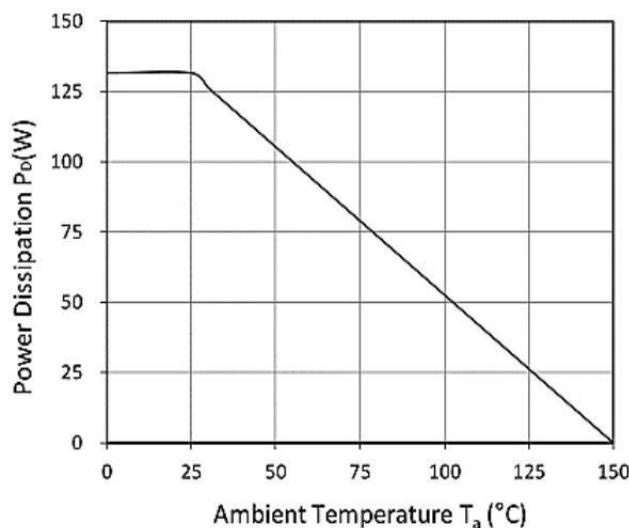
## Typical Characteristics



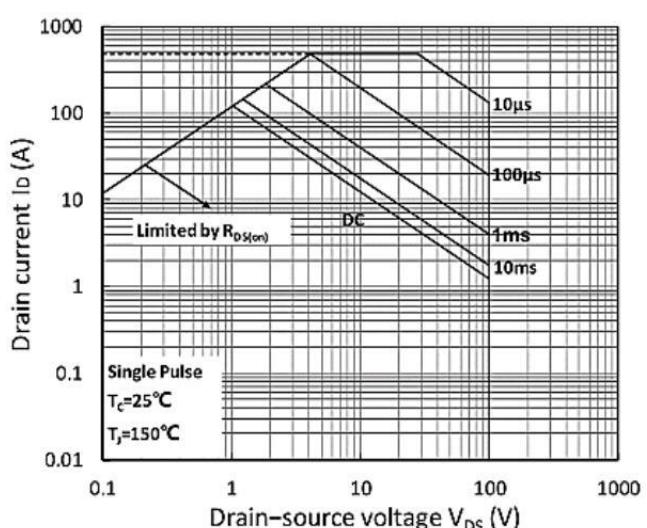
**Figure 7. Capacitance Characteristics**



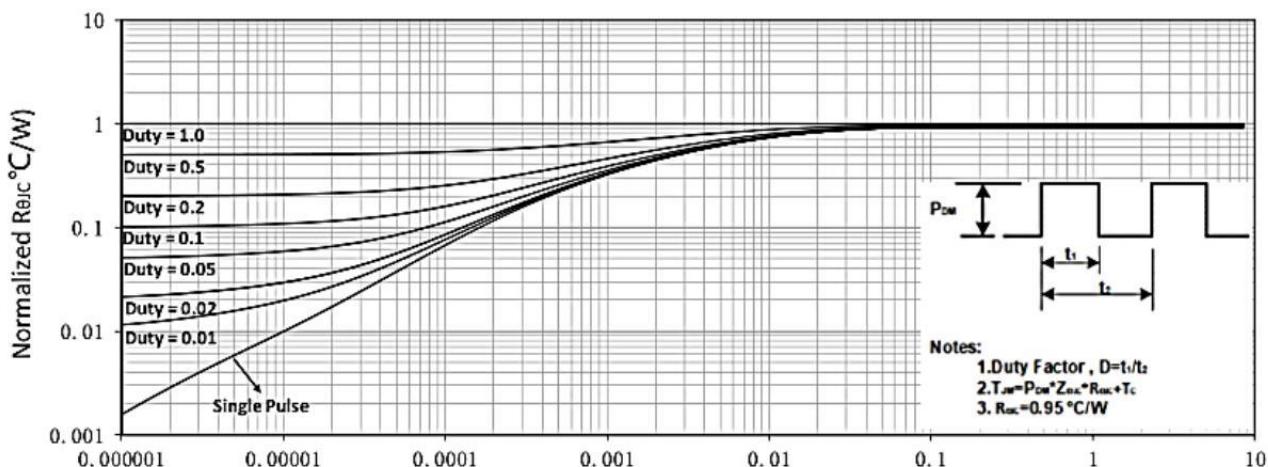
**Figure 8. Gate Charge Characteristics**



**Figure 9. Power Dissipation**

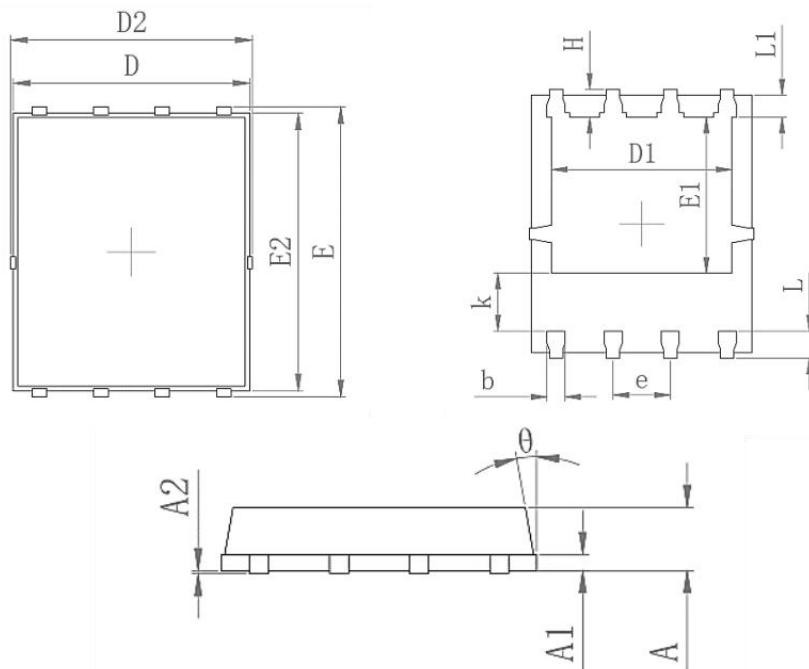


**Figure 10. Safe Operating Area**



**Figure 11. Normalized Maximum Transient Thermal Impedance**

## Package Mechanical Data-PDFN5X6-8L-XZT Single



Symbol	Common mm	
	Mim	Max
A	0.90	1.10
A1	0.254 REF	
A2	0-0.05	
D	4.824	4.976
D1	3.910	4.110
D2	4.944	5.076
E	5.924	6.076
E1	3.375	3.575
E2	5.674	5.826
b	0.350	0.450
e	1.270	
L	0.534	0.686
L1	0.424	0.576
K	1.190	1.390
H	0.549	0.701
Φ	8 °	12 °

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN5*6-8L		5000